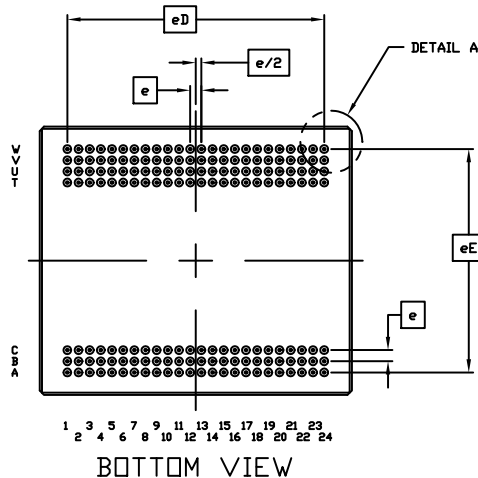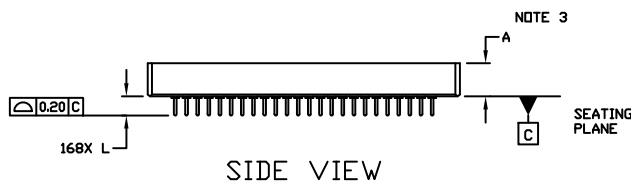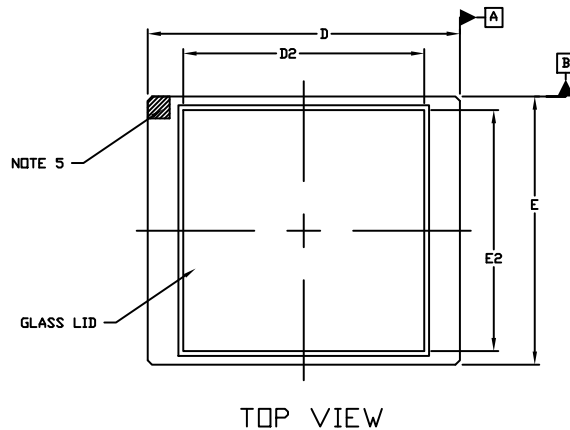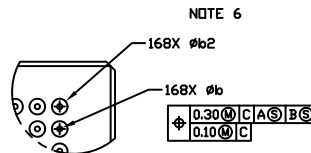**CPGA168, 35.50x30.50**
CASE 107DH
ISSUE O

DATE 30 JUN 2011

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.
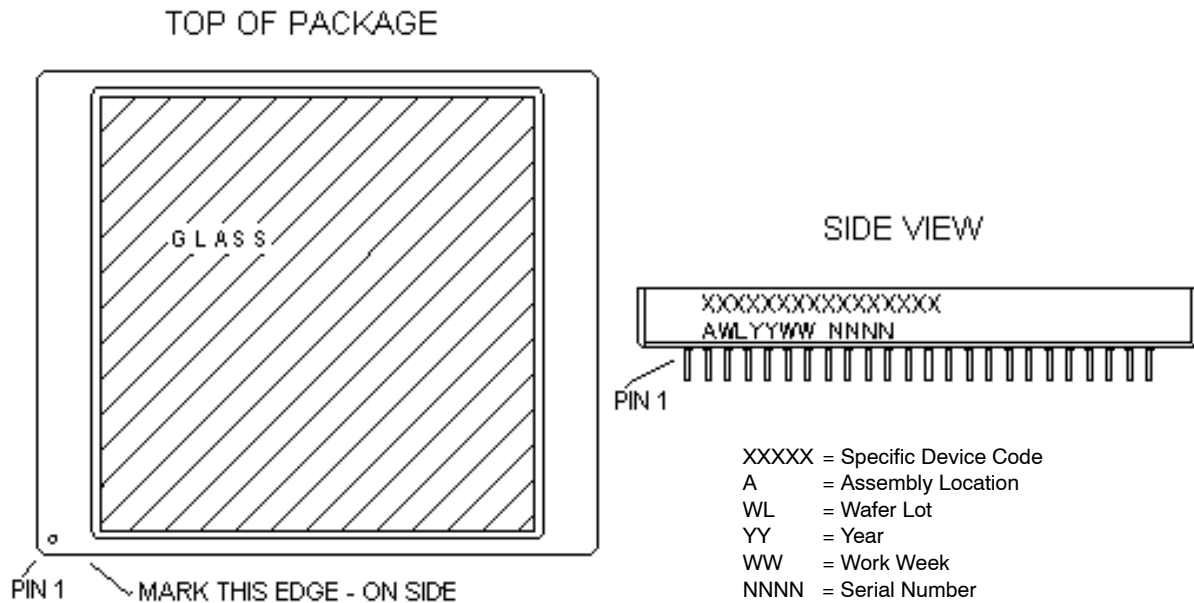6. THIS DIMENSION DEFINES THE MAXIMUM SIZE FOR THE PIN BRAZE PADS.

NOTE 5

GLASS LID

TOP VIEW

NOTE 3

SIDE VIEW

168X L

SEATING PLANE

NOTE 6

168X Øb2
168X Øb

DETAIL A
2X SCALE

DIM	MILLIMETERS	
	MIN.	MAX.
A	3.37	4.13
b	0.25	0.35
b2	---	0.95
D	35.14	35.86
D2	27.40 REF	
E	30.19	30.81
E2	27.40 REF	
e	1.27 BSC	
eD	29.21 BSC	
eE	25.40 BSC	
L	1.83	2.23

BOTTOM VIEW

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24

DETAIL A

GENERIC MARKING
DIAGRAM ON PAGE 2

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**GENERIC
MARKING DIAGRAM**

TOP OF PACKAGE

G L A S S

PIN 1 — MARK THIS EDGE - ON SIDE

SIDE VIEW

XXXXXXXXXXXXXXXX
AWLYYWW NNNN

PIN 1

XXXXX = Specific Device Code
A   = Assembly Location
WL   = Wafer Lot
YY   = Year
WW   = Work Week
NNNN = Serial Number

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